

PATENT NUMBER

JC997 U.S. PTO
 09/902878
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Class	Subclass
ISSUE CLASSIFICATION	

<p>O.I.P.E.</p> <p>SCANNED <i>Torres</i> Q.A.</p>	<p>PATENT DATE</p>
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APPLICATION NO. 09/902878	CONT/PRIOR	CLASS 257	SUBCLASS 678 ⁺	ART UNIT 28TT 2827	EXAMINER CHAMBLISS
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APPLICANTS

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THE

Enhanced thermal dissipation integrated circuit package and method
of manufacturing enhanced thermal dissipation integrated circuit;
package

PTO-2040
12/99

ISSUING CLASSIFICATION															
ORIGINAL				CROSS REFERENCE(S)											
CLASS		SUBCLASS		CLASS	SUBCLASS (ONE SUBCLASS PER BLOCK)										
INTERNATIONAL CLASSIFICATION															

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<input type="checkbox"/> TERMINAL DISCLAIMER	DRAWINGS		CLAIMS ALLOWED	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed. <input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S Patent. No. _____ _____ _____	_____ (Assistant Examiner) (Date) _____ (Primary Examiner) (Date) _____ (Legal Instruments Examiner) (Date)		NOTICE OF ALLOWANCE MAILED	
			ISSUE FEE Amount Due Date Paid	
<input type="checkbox"/> The terminal _____ months of this patent have been disclaimed.				
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